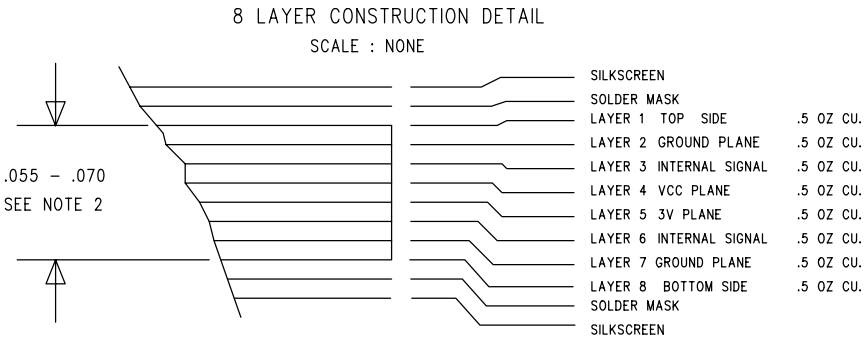
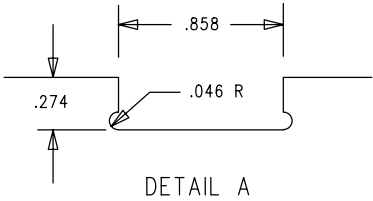
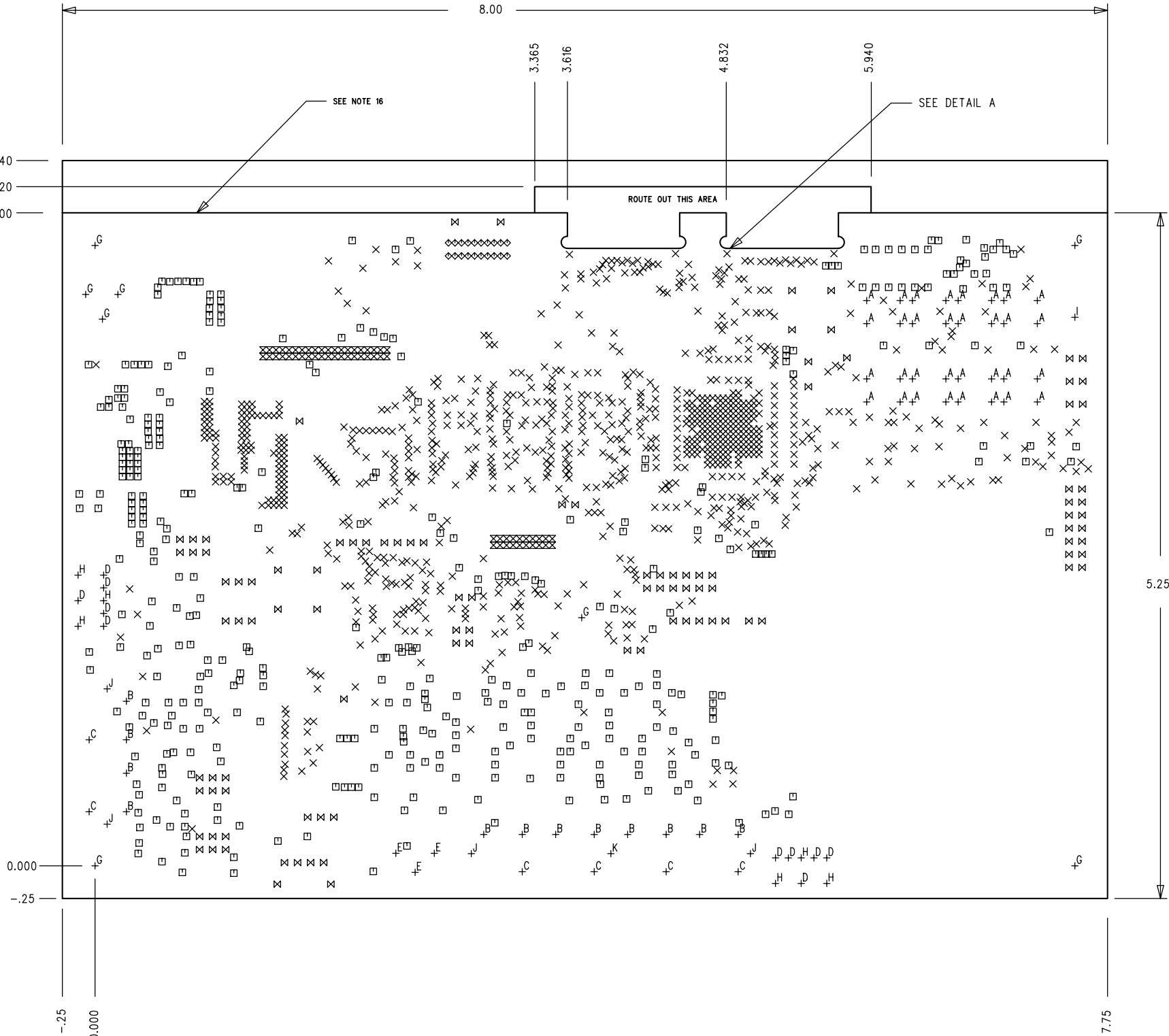



SIZE	QTY	SYM	PLATED	TOL
10	967	✕	YES	+0.003-0.010
14	396	□	YES	+0.003-0.014
22	20	◇	YES	+/-0.003
28	60	⊠	YES	+/-0.003
37	104	⊞	YES	+/-0.003
41	32	+ ^A	YES	+/-0.003
51	12	+ ^B	YES	+/-0.003
59	6	+ ^C	YES	+/-0.003
70	10	+ ^D	YES	+/-0.003
85	3	+ ^E	YES	+/-0.003
125	8	+ ^G	YES	+/-0.005
67	6	+ ^H	NO	+/-0.003
126	1	+ ^I	NO	+/-0.005
140	4	+ ^J	NO	+/-0.005
187	1	+ ^K	NO	+/-0.005



- UNLESS OTHERWISE SPECIFIED
- BOARD TO BE FABRICATED PER IPC-6012A, CLASS 2.
 - MATERIAL: POLYCLAD FR-370HR OR EQUIVALENT. OUTER LAYERS 1/2 OZ/SQFT CU
INNER LAYERS 1/2 OZ/SQFT CU FINISHED .062 (.055 MIN .070 MAX SEE DETAIL).
VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
 - PLATING: ADDITIONAL CU PLATING 1 OZ/SQFT
ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND.
MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE
PER IPC-6012A WITH AMENDMENT 1, CLASS 2 REQUIREMENTS.
WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.
 - FINISH: SURFACES TO BE COATED BY ENIG OF 2 TO 10 MICROINCHES OVER
A MINIMUM OF 60-200 MICROINCHES OF LOW STRESS NICKEL.
 - SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES PER GERBER FILES.
 - SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
 - ARTWORK: MINIMUM FEATURE SIZE = 0.00492
MINIMUM AIR GAP = 0.00475
 - ALL DIMENSIONS ARE IN INCHES.
 - CONTROLLED IMPEDANCE: BOARD TO BE BUILT TO YIELD CONTROLLED IMPEDANCE
OF 60 OHMS +/- 10% ON ALL .00492" LINE WIDTHS
 - DO NOT ADD NON-FUNCTIONAL COPPER THIEVING ON OPEN AREAS OF OUTER LAYERS.
THIEVING IS ALLOWED ON INNER LAYERS, UNLESS OTHERWISE SPECIFIED.
 - VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS.
METHOD 1 IS PREFERRED.
METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER
ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK. AFTER THE
FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERTURES
BOTH SIDES.
METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/IMMERSION
GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS
LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THEN APPLY SOLDER MASK
PLUG ON COMPONENT SIDE.
 - VIA HOLES (.006, .010, .014) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.
 - TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
 - USE IPC-D-356A NETLIST AS SUPPLIED FOR CHECKING.
 - BUILD AS 1-UP PCB.
 - V SCORE 1 LINE ON BOTH SIDES OF THE BOARD. SEE DETAIL.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .XX +/- .010 .XXX +/- .005	CONTRACT NO.		 20 Cotton Road Nashua, New Hampshire 03063 (603) 883-2430 FAX (603) 882-2655	
	APPROVALS	DATE		
MATERIAL	DRAWN	06/26/07	FABRICATION DRAWING 21161N EZ-KIT LITE	
SEE NOTES	CHECKED			
FINISH	ENGINEERING		SIZE B	REV. 3.0
SEE NOTES	QUALITY		DWG. NO.	
DO NOT SCALE THIS DRAWING	MANUFACTURING		SCALE 1 : 1	SHEET 1 OF 1